

Effect of thinning and backplane processing on charge collection properties of irradiated CMOS detectors

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Samples

- test structures from LFoundry demonstrator submission designed by University of Bonn:
 - ❑ Piotr RYMASZEWSKI et al., *Prototype Active Silicon Sensor in 150nm HR-CMOS technology for ATLAS Inner Detector Upgrade*, [2016 JINST 11 C02045](#)
 - ❑ T. Wang et al., *Development of a Depleted Monolithic CMOS Sensor in a 150 nm CMOS Technology for the ATLAS Inner Tracker Upgrade*, [2017 JINST 12 C01039](#)
- 150 nm HR-CMOS technology
- resistivity of p-type substrate > 2 kΩcm
- breakdown voltage from 175 V to over 400 V, depending on the test structure

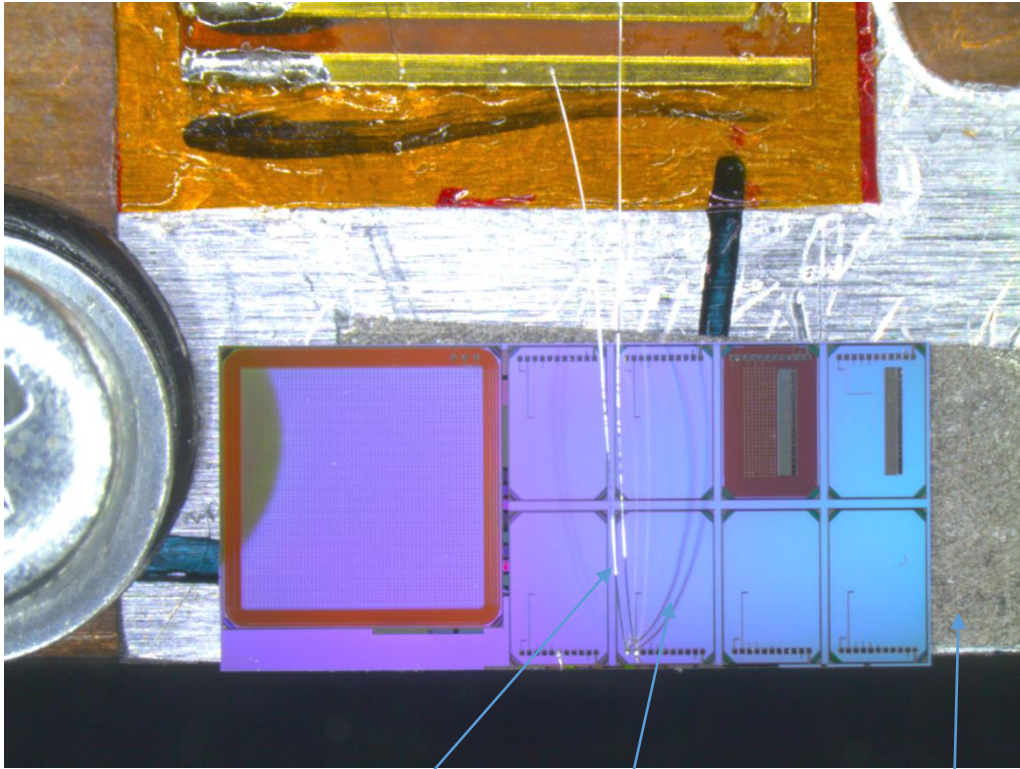
- measurements shown here with passive pixel array

- Two sets:
 - ➔ not thinned (700 μm), no back plane, substrate biased over implant on top
 - ➔ thinned to ~200 μm, back plane processed, bias through the BP

- Samples irradiated with neutrons in TRIGA reactor in Ljubljana

- E-TCT and Sr-90 charge collection measurements

LFoundry passive test structure B



Bond wires to n-wells
(to readout and +HV)

Structure B

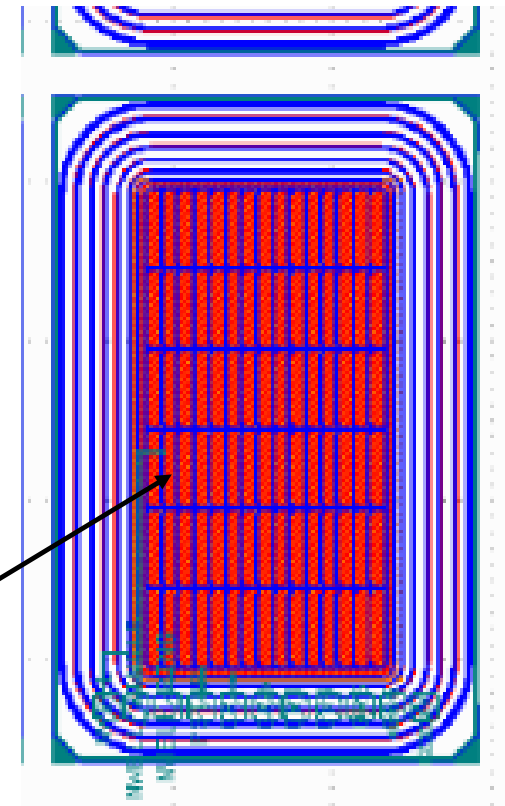
Conductive glue (at GND)

Resistivity 3 k Ω cm
Designed by Bonn

15x6 array of
50x250 μm^2 pixels

Two signal contacts:

- single pixel
- all (89) other pixels

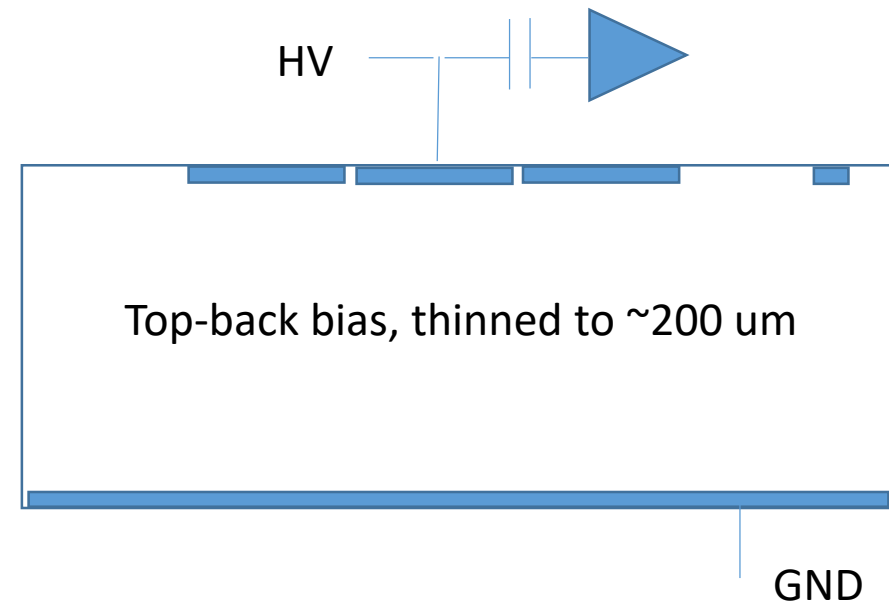
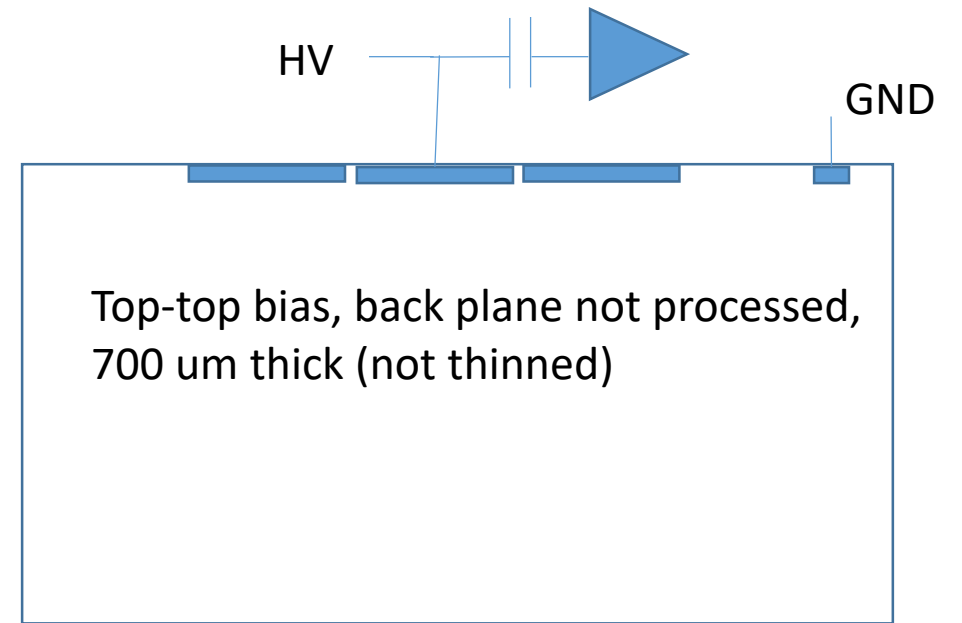
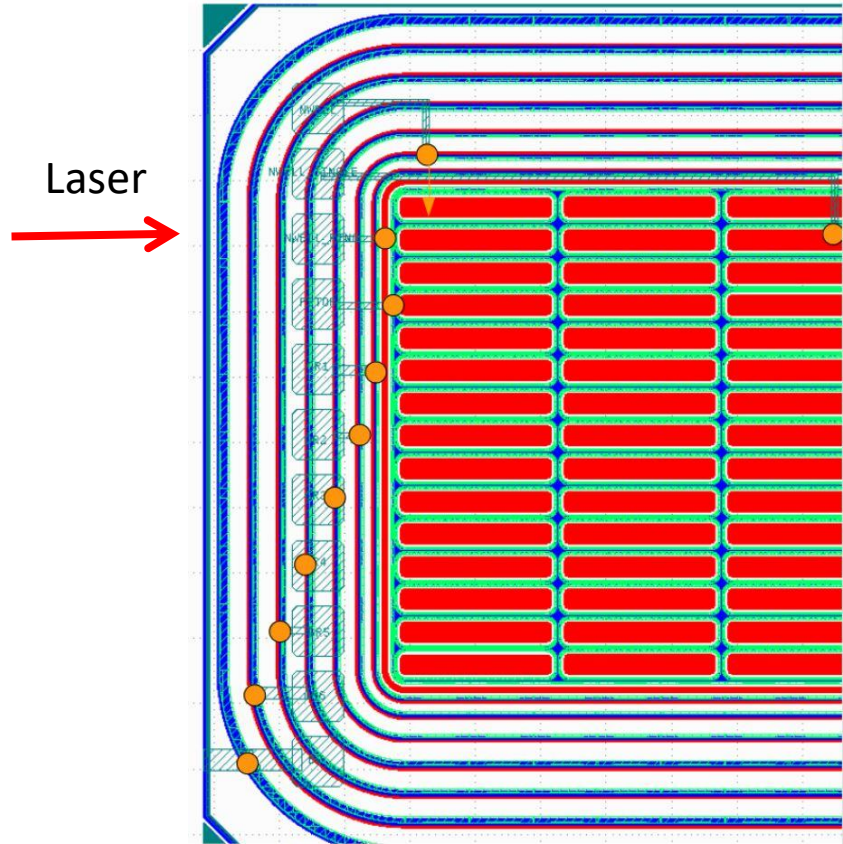


IR laser beam



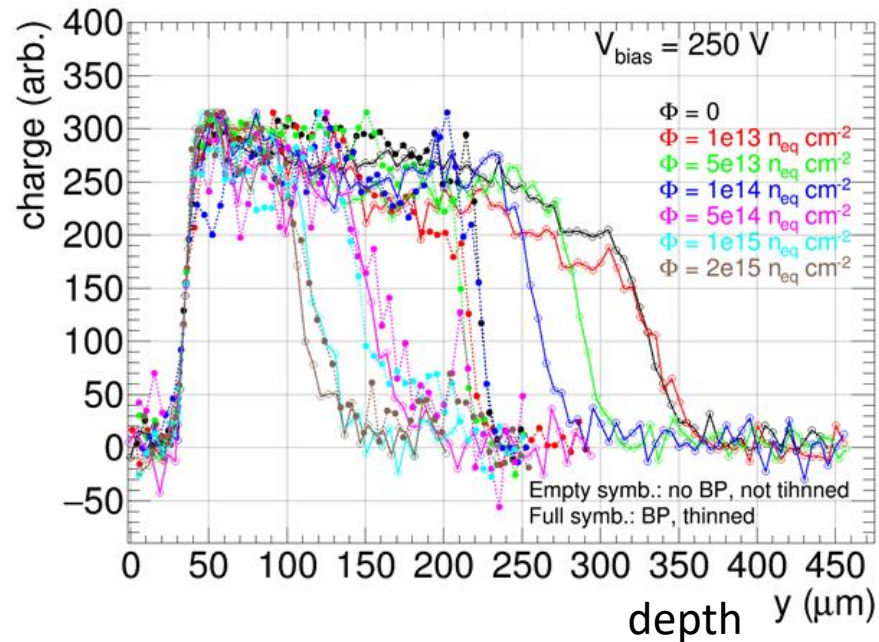
⊙ y-scan
↔ x @ pixel ~centre

LFoundry passive test structure B

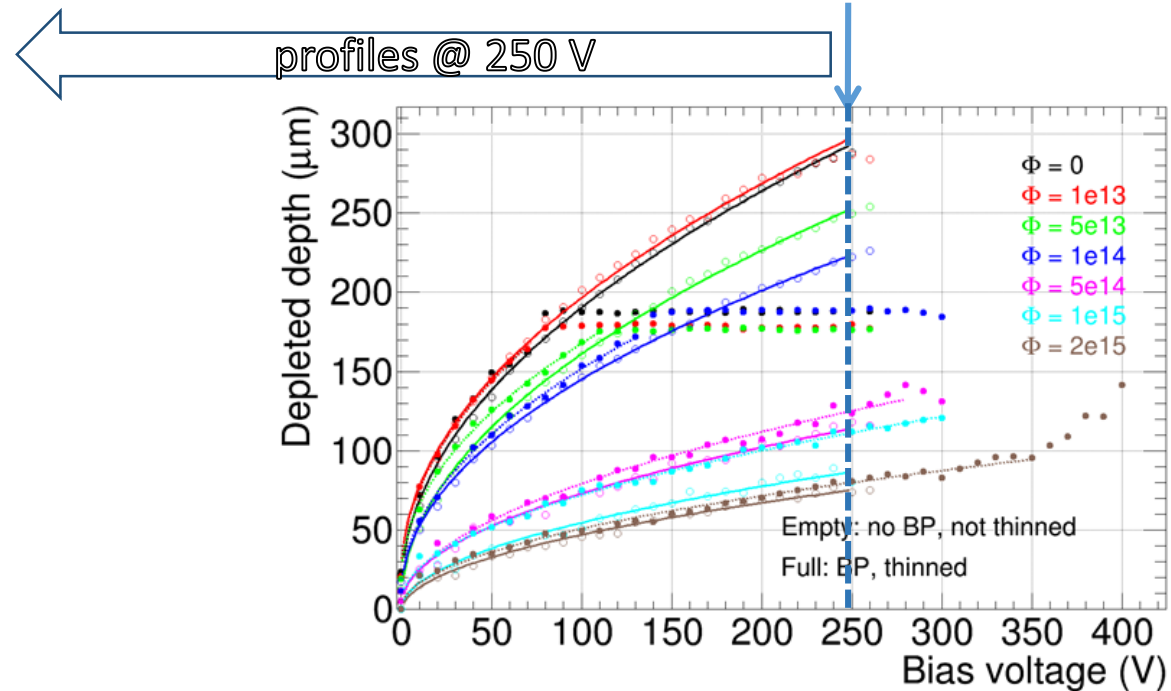


Edge – TCT measurements

- Charge profiles at different fluences
- Depletion depth estimated from width of the profile



- <http://arxiv.org/abs/1801.03671> , submitted to NIM A
- RD50 workshop in Krakow
https://indico.cern.ch/event/637212/contributions/2608669/attachments/1471691/2277507/RD50_June_2017_IM.pdf



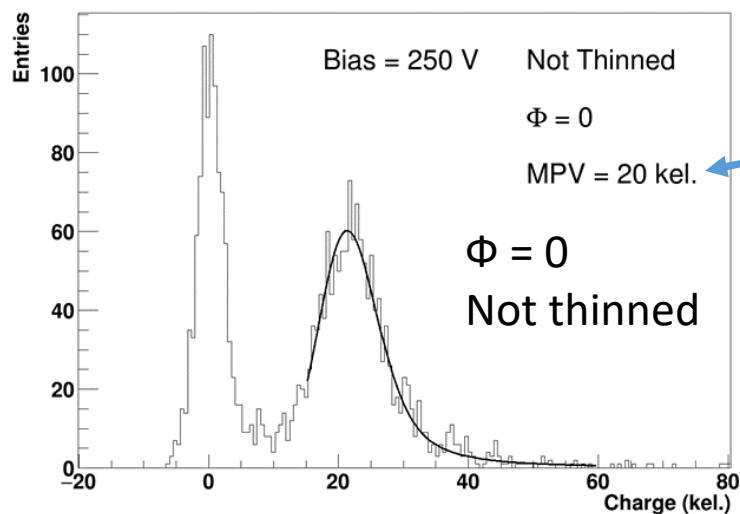
- Charge profiles normalized to same maximum (laser beam monitor not used) !

Charge collection measurements with Sr-90

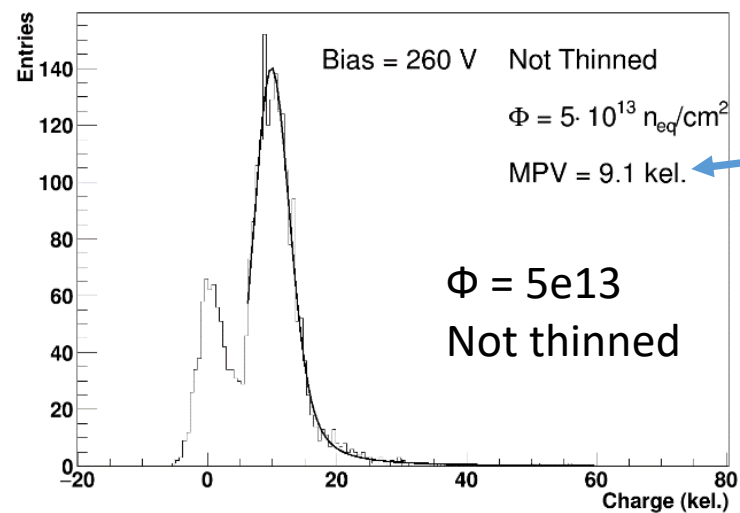
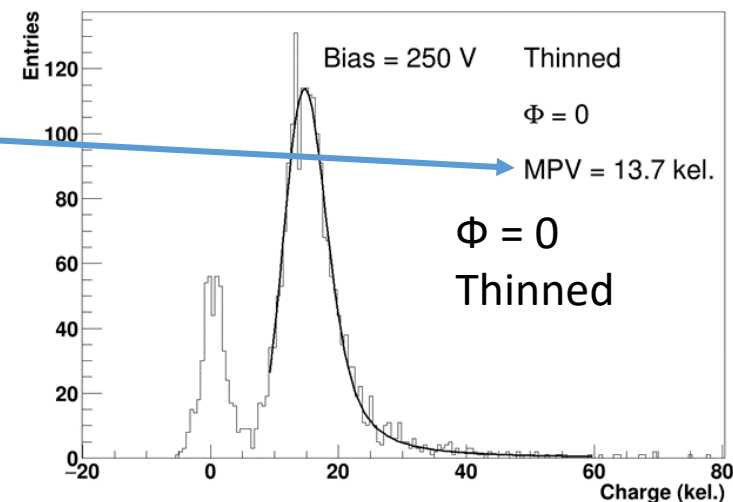
Ortec 142 + 25 ns shaper

More detail in: <http://arxiv.org/abs/1801.03671>

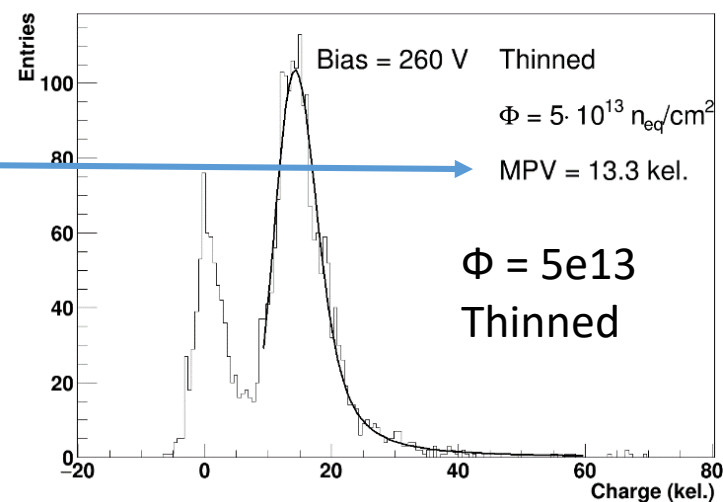
➔ large drop of collected charge after irradiation in non-thinned samples



Before irradiation:
charge as expected from
depletion depth for both
samples



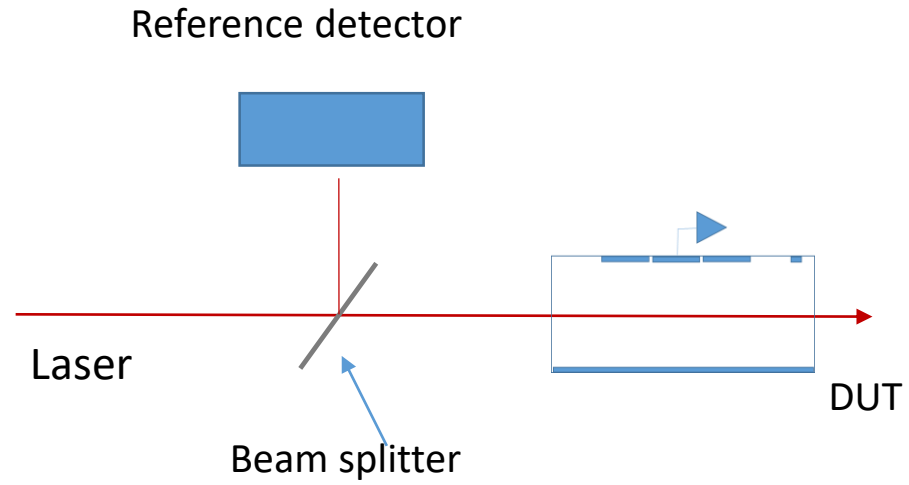
After irradiation:
smaller charge in non-thinned
sample although larger depletion
depth !



fully depleted $\sim 180 \mu\text{m}$ thick

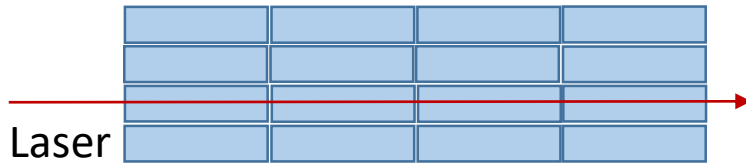
E-TCT: beam monitor

- 1) use beam monitor:
 - can compare signals between detectors
 - but still don't know the charge



- 2) Two readout configurations:

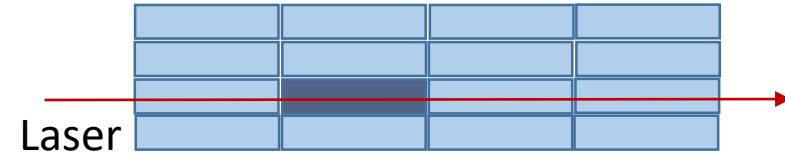
- **all pixels connected together to the readout amp**



Weighting field as in Sr-90 measurements
→ similar to pad detector

- **single pixel**

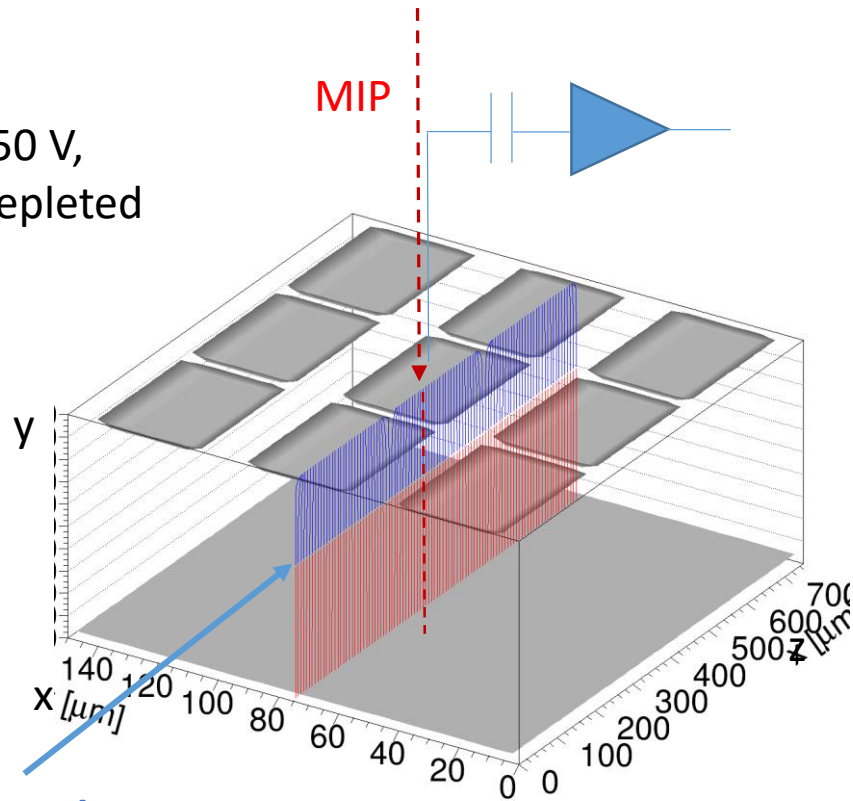
(remaining pixels on same potential but not connected to readout)



More similar to pixel detector in tracking application but:
→ charge generated and drifting also below neighbor pixels affects the induced current pulse on the readout pixel

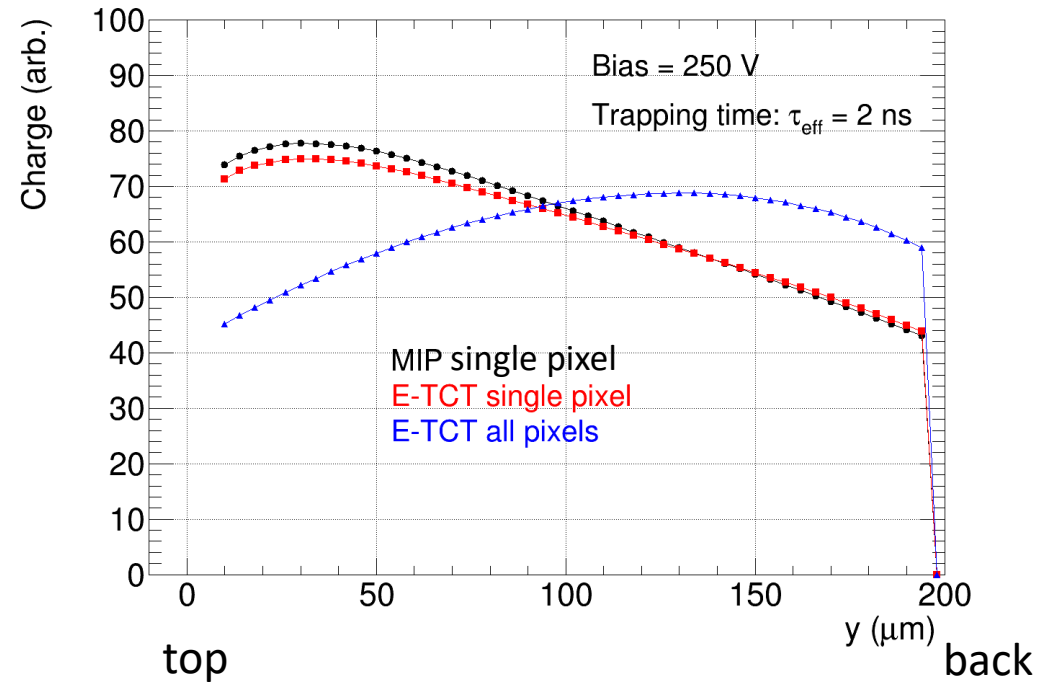
KDetSim simulation (kdetsim.org)

Bias 250 V,
fully depleted



E-TCT Laser beam

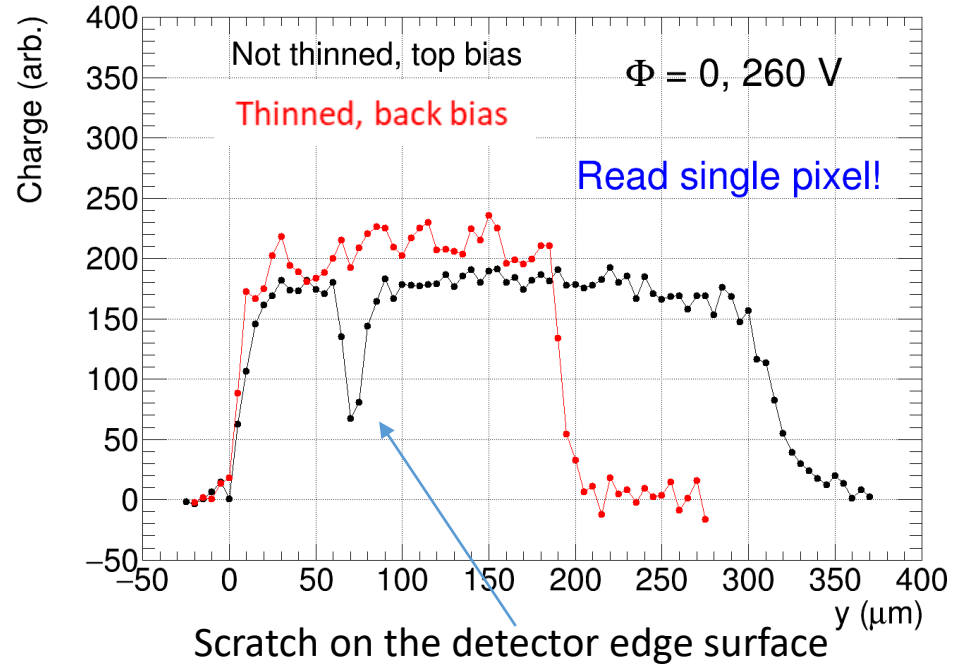
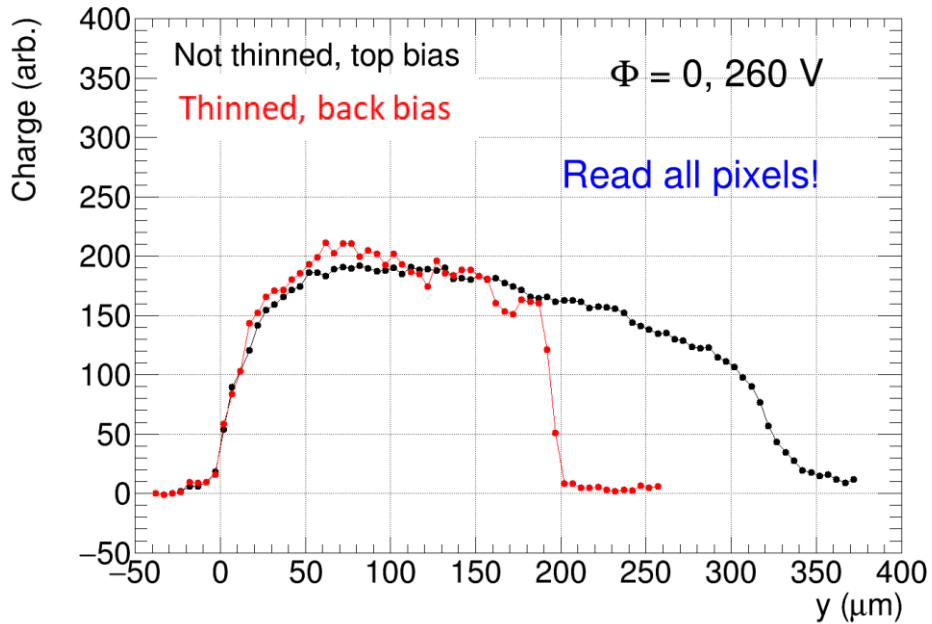
- ➔ MIP – vertical impact through the center of readout pixel
- ➔ E-TCT – charge carriers drift under several pixels



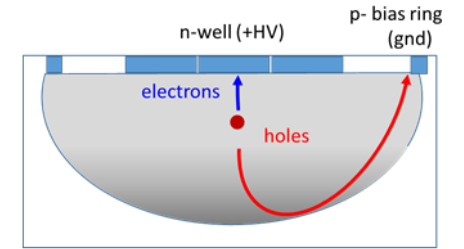
- charge profile in irradiated detector depends on readout configuration (weighting field)
- E-TCT with single pixel readout similar to MIP profile
 - ➔ charge drifting to neighbour pixels doesn't contribute much

E-TCT measurement before irradiation

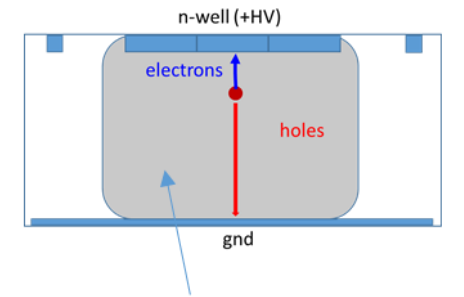
Charge measured with different samples (i.e. red and black in same plot) normalized to same laser power → possible because of laser beam monitor



Not thinned top bias:



Thinned back bias:



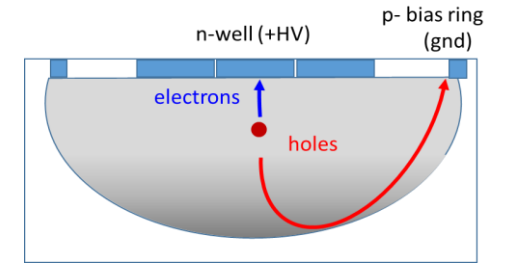
depletion

- same response at same depth for thinned and not thinned (up to the thickness of thin sample)
- all charge collected in 25 ns at all y in both sample
 - carriers must drift across whole weighting field → obvious in thinned fully depleted sample with back bias
 - not thinned top bias: ohmic conductivity of undepleted substrate sufficient to bring low weighting potential near depletion region

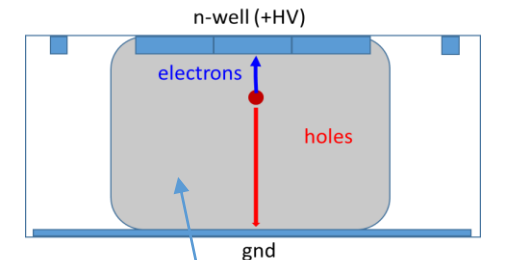
E-TCT measurement after irradiation:

- more charge collected in thinned back-biased sample
 - ➔ in top bias case charge doesn't traverse all weighting field
 - ➔ trapped in the low field region
- difference looks smaller in **single pixel** case
 - ➔ weighting field peaked near the pixel, drift close to n-well contributes more to collected charge

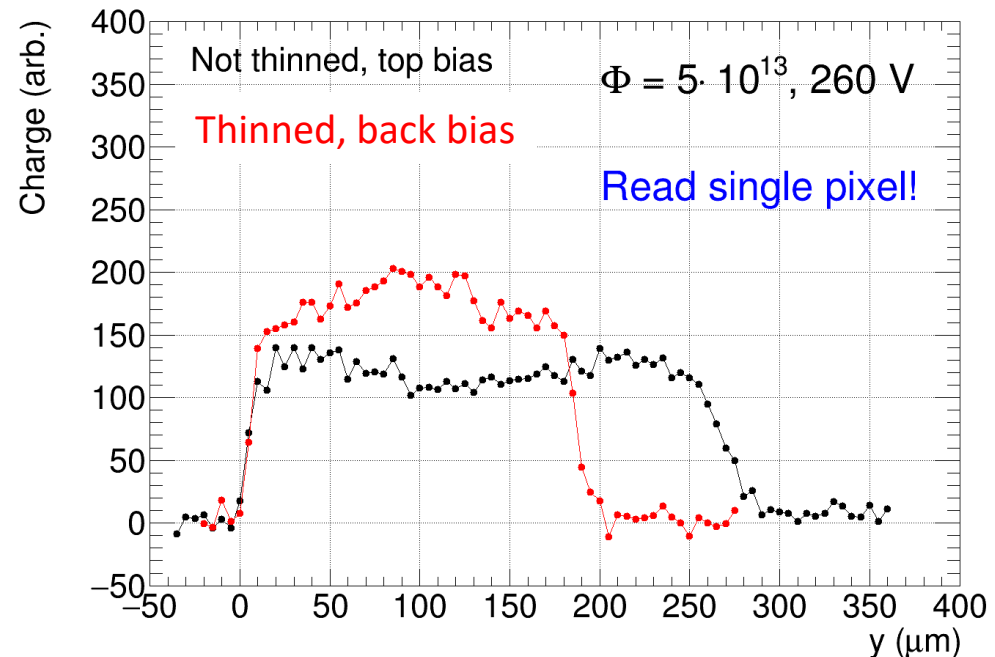
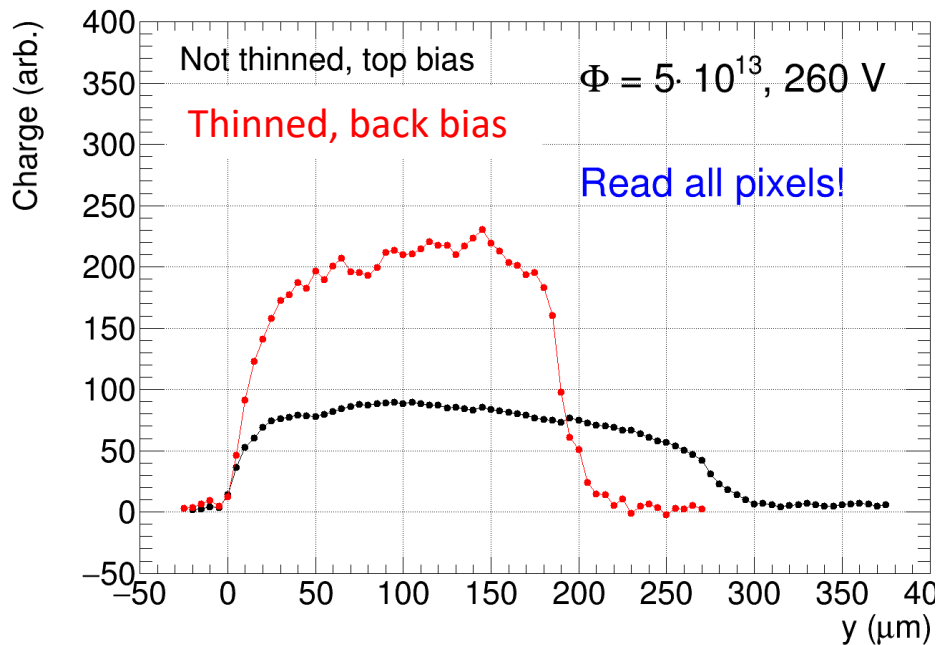
Not thinned top bias:



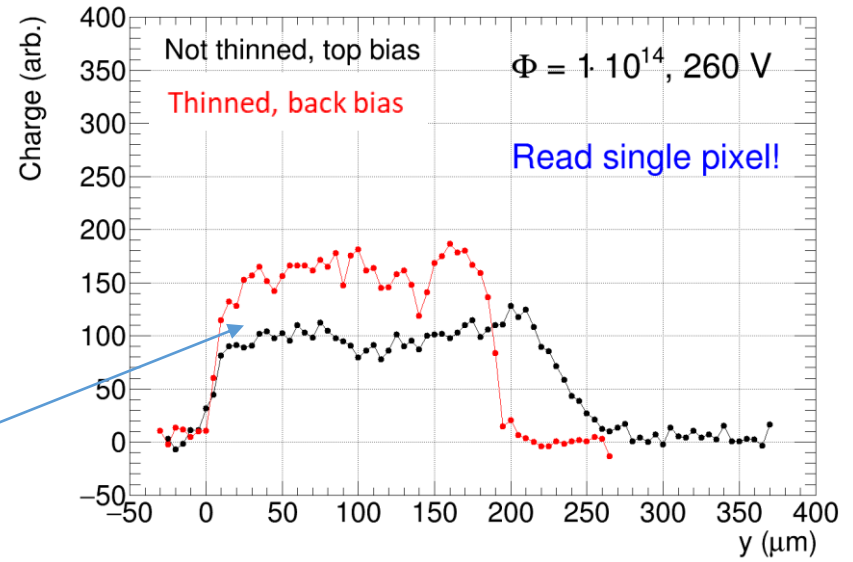
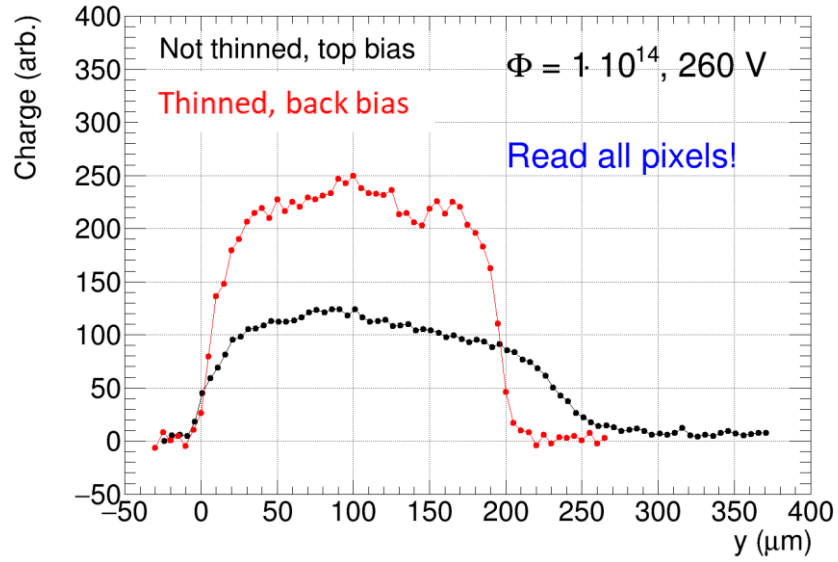
Thinned back bias:



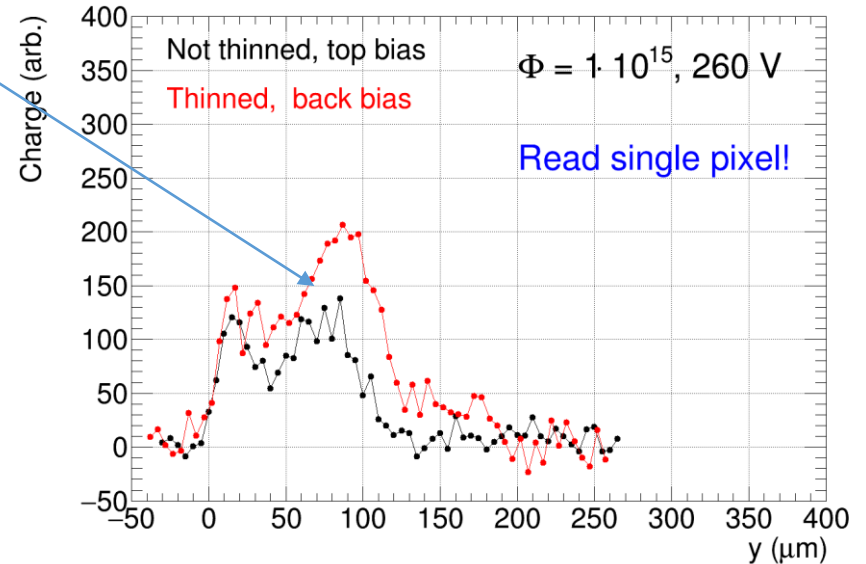
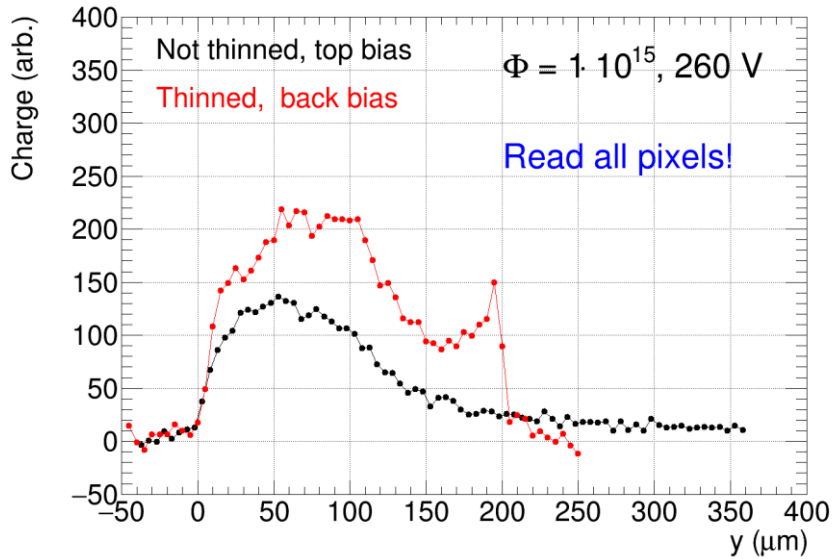
depletion



E-TCT, higher fluences



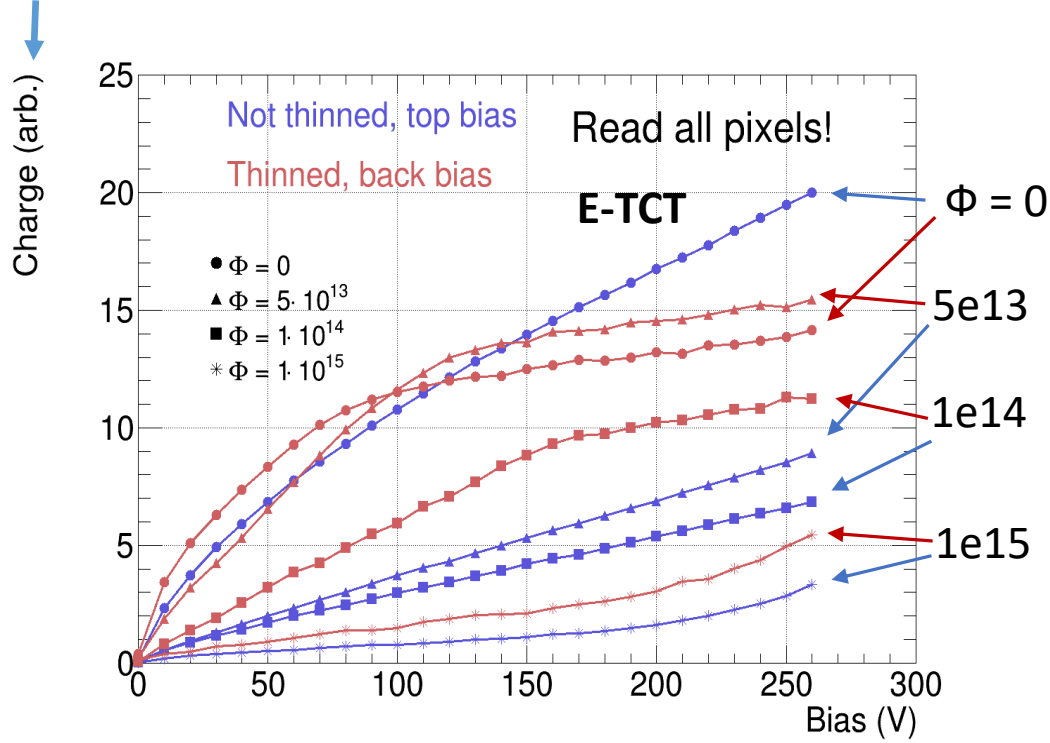
Smaller difference
Between black and red
in single pixel readout!



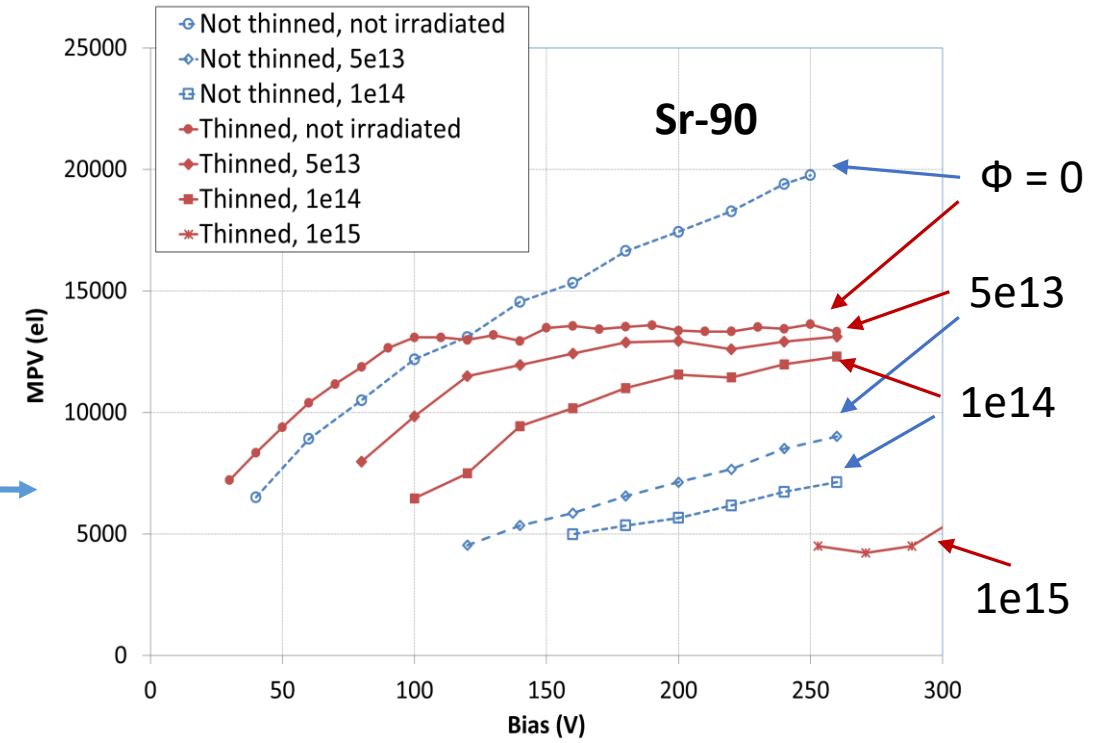
Compare E-TCT with Sr-90 source measurements

- in source measurements charge is generated along the depth of the detector
 → Integrate E-TCT charge profile along y (depth) to get a value comparable with charge measured with Sr-90

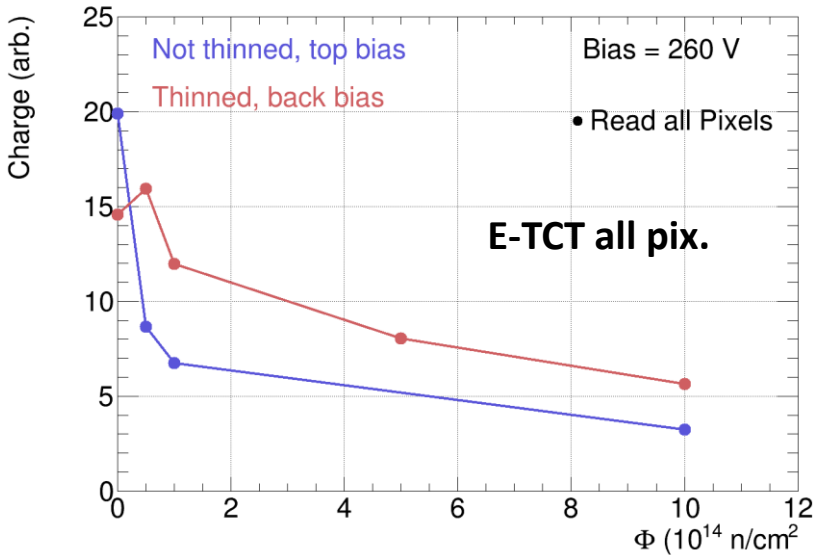
Integral of charge collection profile along y



Consistent!



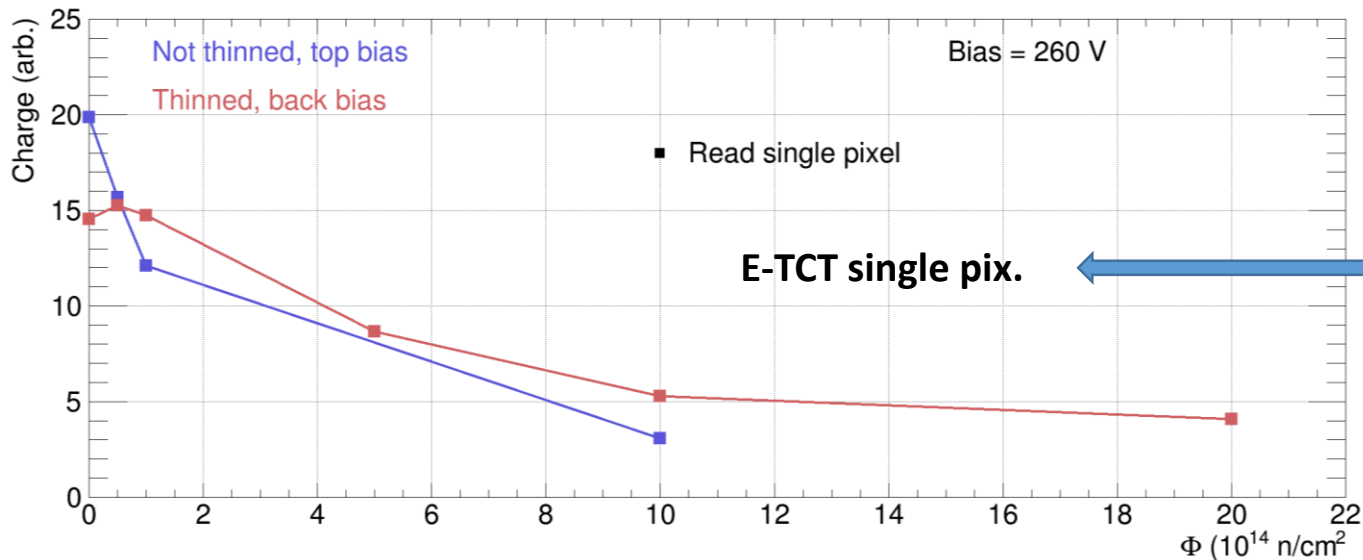
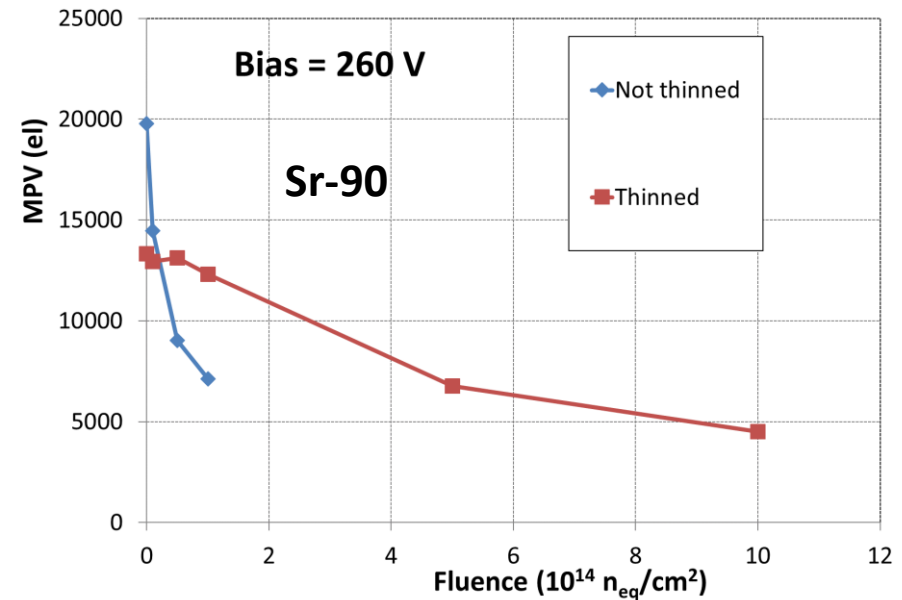
Charge Vs. fluence at 260 V



Similar!

←→

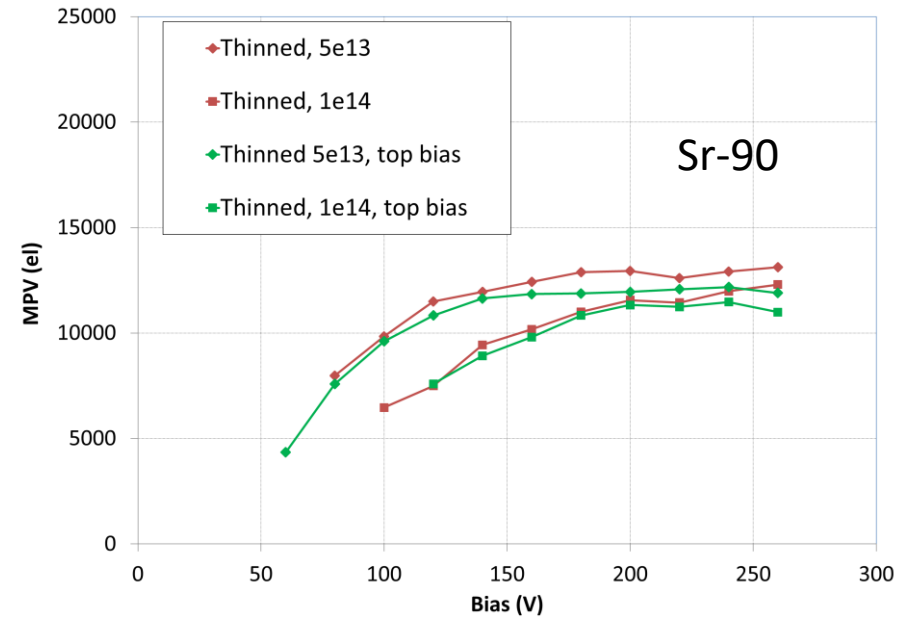
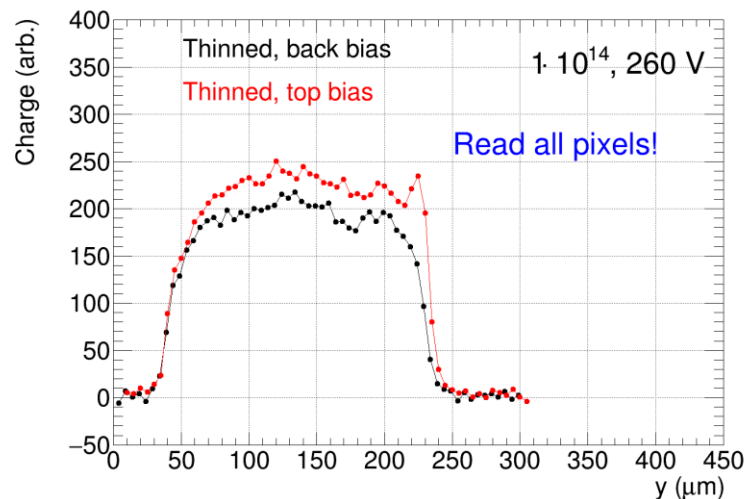
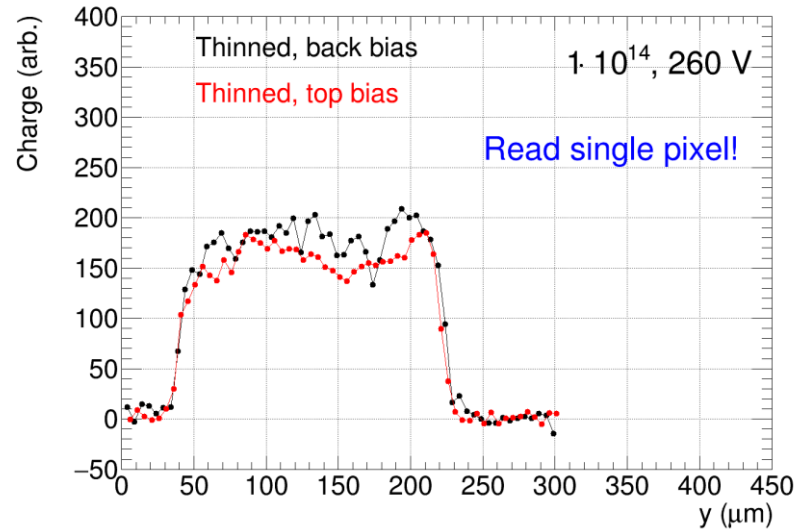
Sr-90 measured with all pixels connected to Readout!



- smaller charge drop in not thinned sample at lower fluences in “single pixel” than in the “all pixel” configuration
- “single pixel” measurement closer to the behavior of real pixel detector in the experiment
 - ➔ single pixel measurements with Sr-90 difficult because pixels are small
 - ➔ test beam needed for MIP response

Backplane but top bias

- Thinn with back plane but **substrate biased via implant on top** as in non-thinned samples (sample mounted on kapton → no contact of backplane with support)



Small difference between top and back bias also when not fully depleted!

- contact with back plane via edge of the device
- equipotential plane at the back
→ modifies electric and weighting field

Summary

- charge collection properties of depleted CMOS structures studied with E-TCT using beam monitor
 - ➔ compare E-TCT measurements with different samples at same laser beam intensity
- study charge collection profiles at different fluences and compare two detector sets and readout configurations
- good agreement of E-TCT and Sr-90 source measurements
 - ➔ thinning and backplane improves charge collection after irradiation
 - ➔ better charge collection also if backplane floating and substrate contacted from top
 - ➔ effect less significant in “single pixel” configuration because of weighting field (small pixel effect)
 - ➔ charge collection estimated with E-TCT in “single pixel” readout should give good estimate for tracking application and it is much simpler than test beam measurement